

[CHIP STRUCTURE]

Abstract

A chip structure comprising a chip, a spacing pad, a passivation layer, an under-bump metallic (UBM) layer and a conductive bump is provided. A plurality of bonding pads is disposed on the active surface of the chip. The spacing pad is disposed between the bonding pad and the UBM layer for reducing the possibility of broken circuit caused by the electro-migration between the bonding pad and the UBM layer. The base of the conductive bump is connected to the UBM layer so that the conductive bump can serve as a conductive structure for connecting with an external circuit.